

Winding Type Chip Inductor

SWF2012RIF-SERIES-X5

1. Features

1. Ferrite core wire wound construction.
2. High Reliability due to wire wound type construction.
3. Small footprint as well as low profile.
4. 100% Lead(Pb) & Halogen-Free and RoHS compliant.
5. Operating temperature -40~+125°C (Including self - temperature rise)
6. These products provide low DC resistance and high current.
7. Precision inductance tolerance is available.
8. Application for DC power line.

Digital camera and other electronic equipment

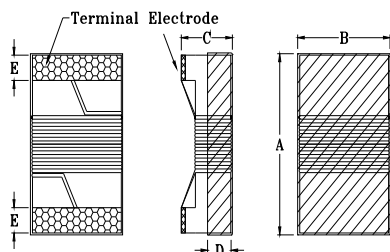
Personal computers, Hard disk drives

Mobile Device / Handheld Device / LowProfile Device / Panel

xDSL modem and Cable modem



2. Dimensions



Size	A	B	C	D	E
SWF2012	2.20±0.20	1.40±0.20	1.30±0.10	0.65ref.	0.50±0.10

Unit:mm

3. Part Numbering

SWF	2012	R	I	F	-	2R2	-	N	X5
A	B	C	D	E		F		G	H

A: Series

B: Dimension

L x W

C: Control S/N

D: Material

I3C

E: Lead free type

F: Inductance

2R2=2.2 uH

G: Inductance Tolerance

L=+15%-5%, N=+20%-0%

H: Control S/N

4. Specification

TAI-TECH Part Number	Inductance (uH)	Tolerance	Test Frequency (Hz)	Q/MHz Typ.	SRF (MHz) Typ.	DCR (Ω) ±30%.	IDC (mA) Typ.	Irms (mA) Typ.
SWF2012RIF-R10-□X5	0.10	L,N	0.5V/7.9M	10/7.9	1600	0.06	1900	2000
SWF2012RIF-R22-□X5	0.22	L,N	0.5V/7.9M	13/7.9	1550	0.08	1600	1700
SWF2012RIF-R33-□X5	0.33	L,N	0.5V/7.9M	13/7.9	1150	0.09	1400	1500
SWF2012RIF-R47-□X5	0.47	L,N	0.5V/7.9M	13/7.9	800	0.10	1300	1400

TAI-TECH Part Number	Inductance (uH)	Tolerance	Test Frequency (Hz)	Q/MHz Typ.	SRF (MHz) Typ.	DCR (Ω) $\pm 30\%$	IDC (mA) Typ.	I _{rms} (mA) Typ.
SWF2012RIF-R56-□X5	0.56	L,N	0.5V/7.9M	13/7.9	750	0.13	1200	1300
SWF2012RIF-R68-□X5	0.68	L,N	0.5V/7.9M	13/7.9	700	0.14	1100	1200
SWF2012RIF-R82-□X5	0.82	L,N	0.5V/7.9M	13/7.9	350	0.15	1000	1100
SWF2012RIF-1R0-□X5	1.00	L,N	0.5V/7.9M	14/7.9	208	0.13	1100	1300
SWF2012RIF-2R2-□X5	2.20	L,N	0.5V/7.9M	13/7.9	87	0.22	740	1040
SWF2012RIF-3R3-□X5	3.30	L,N	0.5V/7.9M	12/7.9	70	0.30	620	800
SWF2012RIF-4R7-□X5	4.70	L,N	0.5V/7.9M	14/7.9	51	0.43	520	840
SWF2012RIF-6R8-□X5	6.80	L,N	0.5V/7.9M	14/7.9	46	0.68	420	700
SWF2012RIF-8R2-□X5	8.20	L,N	0.5V/7.9M	14/7.9	33	0.73	400	680
SWF2012RIF-100-□X5	10.0	L,N	0.5V/2.5M	14/2.5	31	0.85	360	560
SWF2012RIF-150-□X5	15.0	L,N	0.5V/2.5M	15/2.5	28	1.40	300	380
SWF2012RIF-220-□X5	22.0	L,N	0.5V/2.5M	15/2.5	20	1.76	240	340

Note:

Measurement board data

Material : FR4

Board dimensions : 100 X 50 X 1.6t mm

Pattern dimensions: 45 X 30 mm (Double side board)

Pattern thickness : 50 μ m

5. Recommended PC Board Pattern

Chip size							Land Patterns For Reflow Soldering		
Series	Type	A(mm)	B(mm)	C(mm)	D(mm)	E(mm)	L(mm)	G(mm)	H(mm)
SWF	2012	2.20 $\pm$ 0.2	1.40 $\pm$ 0.2	1.30 $\pm$ 0.1	0.65 ref.	0.50 $\pm$ 0.1	2.80	0.96	1.78

